# imall

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## Panasonic

## MOS FET MTM761230LBF

## MTM761230LBF Silicon P-channel MOSFET

### For Switching

#### Features

- Low drain-source On-state Resistance : RDS(on) typ. =  $36 \text{ m}\Omega$  (VGS = -4 V)
- Low drive voltage : 2.5 V drive
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)
- Marking Symbol :9C

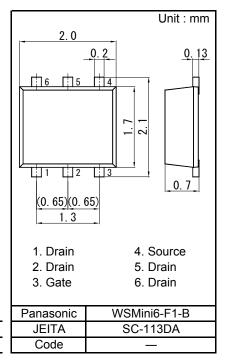
#### Packaging

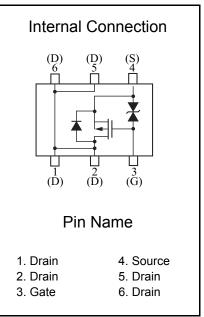
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C							
Parameter	Symbol	Rating	Unit				
Drain to Source Voltage	VDS	-20	V				
Gate to Source Voltage	VGS	±10	V				
Drain Current	ID	-3	Α				
Drain Current (Pulsed) <sup>*1</sup>	IDp	-16	Α				
Total Power Dissipation *2	PD	700	mW				
Channel Temperature	Tch	150	°C				
Operating Ambient Temperature	Topr	-40 to +85	°C				
Storage Temperature Range	Tstg	-55 to +150	°C				
Note) *1 Dules width < 10 s Duty sures < 1	0/						

Note) \*1 Pulse width  $\leq$  10  $\mu s,$  Duty cycle  $\leq$  1 %

\*2 Measuring on ceramic board at 40 mm × 38 mm × 0.1 mm Absolute maximum rating PD Non-heat sink shall be made 150 mW.





## **Panasonic**

# MOS FET MTM761230LBF

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = -1 mA, VGS = 0 V	-20			V
Zero Gate Voltage Drain Current	IDSS	VDS = -20 V, VGS = 0 V			-1	μA
Gate-source Leakage Current	IGSS	VGS = ±8 V, VDS = 0 V			±10	μA
Gate-source Threshold Voltage	Vth	ID = -1 mA, VDS = -10 V	-0.4	-0.85	-1.3	V
Drain-source On-state Resistance <sup>*1</sup>	RDS(on)1	ID = -1 A, VGS = -4 V		36	55	mΩ
	RDS(on)2	ID = -0.5 A, VGS = -2.5 V		42	70	
Forward transfer admittance <sup>*1</sup>	Yfs	ID = -1 A, VDS = -10 V, f = 1 kHz	3.5			S
Input Capacitance	Ciss	VDS = -10 V, VGS = 0 V		1 000		pF
Output Capacitance	Coss	f = 1 MHz		100		
Reverse Transfer Capacitance	Crss			100		
Turn-on Delay Time <sup>*2</sup>	ton	VDD = -10 V, VGS = 0 to -4 V ID = -1 A		30		ns
Turn-off Delay Time <sup>*2</sup>	toff	VDD = -10 V, VGS = -4 to 0 V ID = -1 A		250		ns

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Pulse test : Pulse width  $\leq$  300  $\mu s,$  Duty cycle  $\leq$  2 %

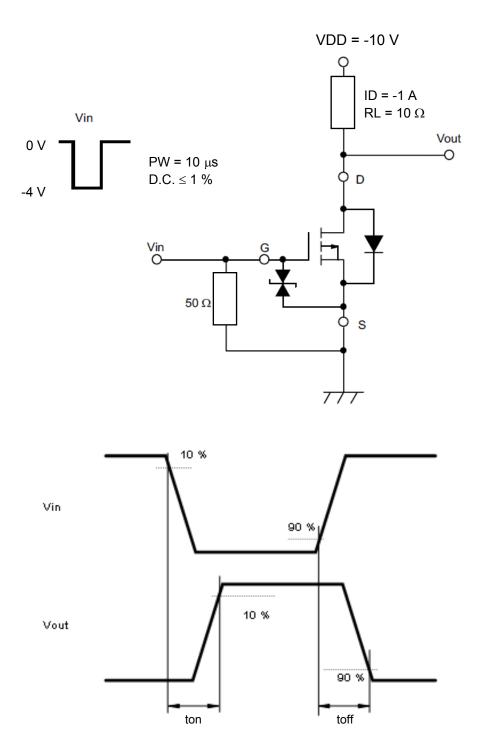
\*2 Measurement circuit for Turn-on Delay Time / Turn-off Delay Time

Doc No. TT4-EA-10073 Revision. 2



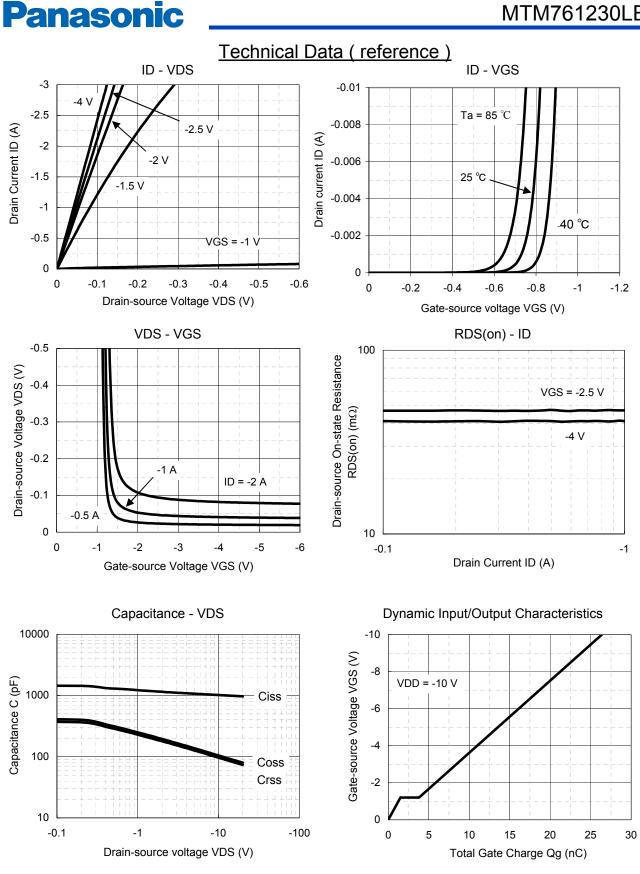
MOS FET MTM761230LBF

\*2 Measurement circuit for Turn-on Delay Time / Turn-off Delay Time



Established : 2007-11-07 Revised : 2013-06-18

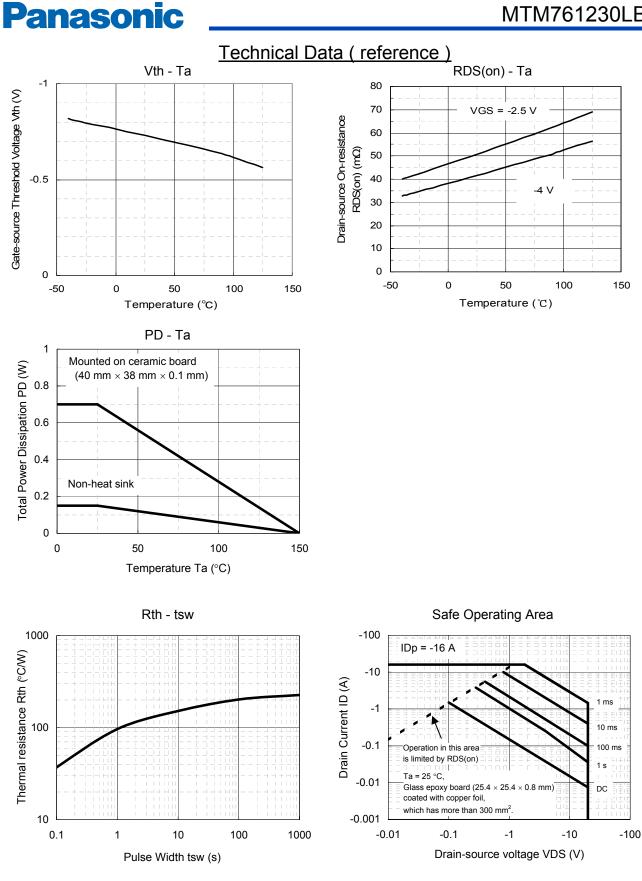




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Established : 2007-11-07 Revised : 2013-06-18



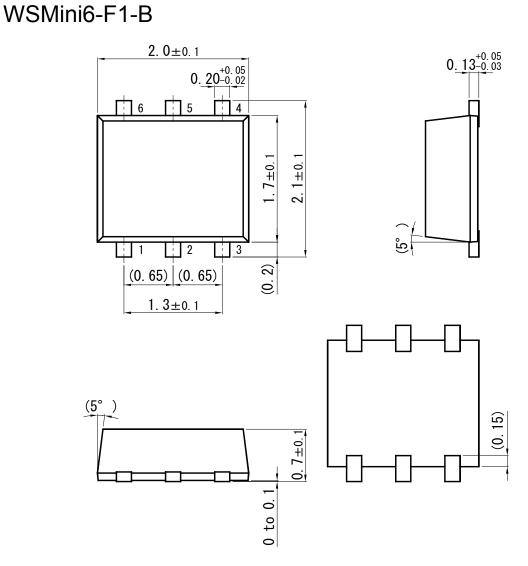


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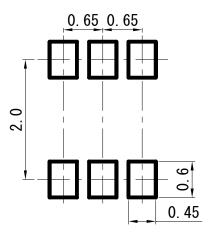
Established : 2007 -11 -07 Revised : 2013 - 06 - 18



MOS FET MTM761230LBF



Land Pattern (Reference) (Unit : mm)



Unit : mm

Established : 2007-11-07 Revised : 2013-06-18

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